

IN THE CLAIMS

1. (currently amended): A circuit board for mounting a semiconductor chip, the circuit board including

an insulating substrate having a surface, the surface including mutually non-overlapping regions, the regions including

a semiconductor chip region [[on]] of the surface of the insulating substrate for mounting the semiconductor chip, and

at least one wiring region [[on]] of the surface of the insulating substrate in which wirings electrically connectable to the semiconductor chip are formed on top of the surface, and

at least one reinforcement layer region [[on]] of the surface of the insulating substrate in which reinforcement layers for maintaining the strength of the circuit board for mounting the semiconductor chip are formed; and

a protective film that covers the wirings and the reinforcement layer.

2. (previously presented): The circuit board for mounting a semiconductor chip of claim 1, the comprising a semiconductor chip that covers part of the wiring region.

3. (previously presented): The circuit board for mounting a semiconductor chip of claim 1, wherein the reinforcement layers comprise copper wirings.

4. (original): The circuit board for mounting a semiconductor chip of claim 1, wherein the protective film is planarized.

5. (original): The circuit board for mounting a semiconductor chip of claim 1, wherein a surface of the protective film is planarized by being cut and polished.

6. (currently amended): A method of manufacturing a circuit board for mounting a semiconductor chip, the circuit board including an insulating substrate having a surface, the surface including mutually non-overlapping regions, the regions including a semiconductor chip region of the surface of the insulating substrate for mounting the semiconductor chip, at least one reinforcement layer region of the surface of the insulating substrate in which reinforcement layers for maintaining the strength of the insulating substrate for mounting the semiconductor chip are formed, and at least one wiring region of the surface of the insulating substrate in which wirings electrically connected to the semiconductor chip are formed on top of the surface, the method comprising:

forming the wirings in the wiring region disposed in a vicinity of the semiconductor chip region;

forming the reinforcement layers in the reinforcement layer region disposed in a vicinity of the wiring region; and

forming a protective film that covers the wirings and the reinforcement layer.

7. (original): The manufacturing method of claim 6, further including a step of planarizing the protective film.

8. (original): The manufacturing method of claim 7, wherein the planarization is carried out by cutting and polishing a surface of the protective film.

9. (previously presented): A circuit board for mounting a semiconductor chip, the circuit board comprising:

an insulating substrate, the insulating substrate having a top surface and a bottom surface, with the top surface including mutually separated first, second and third regions on the insulating substrate;

wirings provided in the second region on the top surface of the insulating substrate, with the semiconductor chip being electrically connected to the wirings;

reinforcement layers provided only in the third region on the top surface of the insulating substrate, with the reinforcement layers maintaining the strength of the circuit board for mounting a semiconductor chip;

a protective film formed on the insulating substrate so as to cover the wirings and the reinforcement layers; and

the semiconductor chip mounted on the protective film above the first region on the top surface of the insulating substrate,

wherein the third region encloses the first region and the second region.

10. (original): The circuit board for mounting a semiconductor chip of claim 9, wherein the protective film is planarized.

11. (original): The circuit board for mounting a semiconductor chip of claim 9, wherein the protective film is a solder resist.

12. (original): The circuit board for mounting a semiconductor chip of claim 9, wherein the reinforcement layers comprise a metal.

13. (original): The circuit board for mounting a semiconductor chip of claim 9, wherein the reinforcement layers comprise conductive materials.

14. (original): The circuit board for mounting a semiconductor chip of claim 9, wherein the reinforcement layers comprise insulating materials.

15. (original): The circuit board for mounting a semiconductor chip of claim 9, further comprising solder balls that are disposed on the bottom surface of the insulating substrate and electrically connected to the wirings.

16. (previously presented): The circuit board for mounting a semiconductor chip of claim 1, wherein the wiring region is disposed in a vicinity of the semiconductor chip region and the reinforcement layer region is disposed in vicinity of the wiring region.

17. (previously presented): The circuit board for mounting a semiconductor chip of claim 1, wherein the wiring region is disposed between the semiconductor chip region and the reinforcement layer region.

18. (previously presented): The circuit board for mounting a semiconductor chip of claim 1, wherein the reinforcement layer region encloses the wiring region and the semiconductor chip region.

19. (previously presented): The circuit board for mounting a semiconductor chip of claim 1, wherein the semiconductor chip region does not overlap the wiring region.

20. (new): The circuit board for mounting a semiconductor chip of claim 1, wherein the protective film is not planarized over the wirings and the reinforcement layer.

21. (new): The manufacturing method of claim 6, not including any step of planarizing the protective film over the wirings and the reinforcement layer.

22. (new): The circuit board for mounting a semiconductor chip of claim 9, wherein the protective film is not planarized over the wirings and the reinforcement layer.